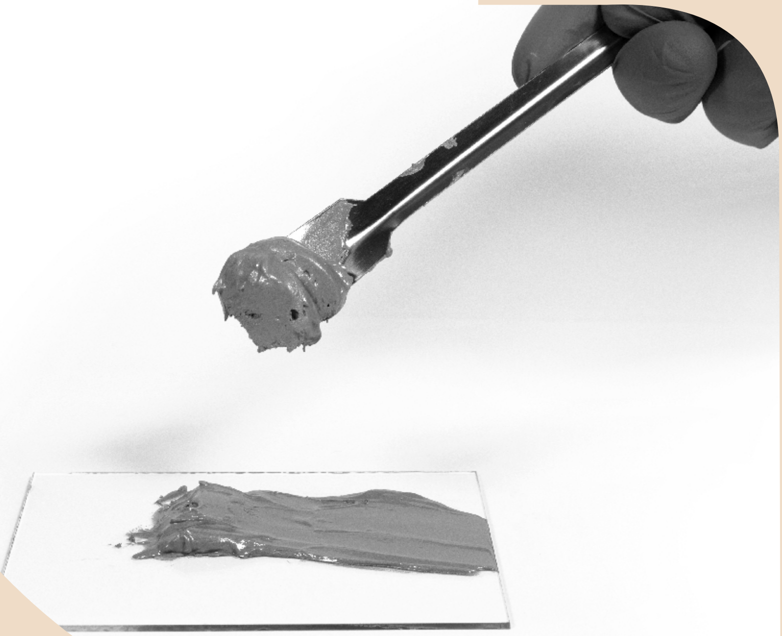
NEXT

SCAN TO SEE
ON YOUR PHONE



Gold-Tin

SOLDER PASTE

Gold-tin solder paste is used in a variety of high-reliability applications, where its high melting point, non-creep, high-tensile stress, thermal and electrical conductivity, as well as proven usage life makes it a standard “known-good” material.

nano
shel

G

Gold-Tin
SOLDERPASTE

CATALOGUE NO.

- **NS6130-01-157**

SPECS

- ✓ Purity: 99.9%
- ✓ Particle Size: 80-100nm
- ✓ Shape: Spherical
- ✓ Melting Point: Sn20/Au80 = 280°C,
- ✓ Sn25/Au75= 280°C
- ✓ Composition: Sn20/Au80
- ✓ Density: Sn20/Au80 = 7.4 g/cc,
- ✓ Sn25/Au75 = 7.4 g/cc

All types of particles size are available in micro and nano range.

Applications

- ✓ Superior thermal conductivity
- ✓ Resistance to corrosion
- ✓ Superior thermal fatigue resistance
- ✓ Good joint strength
- ✓ Excellent wetting properties
- ✓ Resistance to oxidation

NANOSHEL®
Creating Miracles in Black

/nanoshel

SCAN TO SEE ON YOUR PHONE

> NEXT

www.nanoshel.com | sales@nanoshel.com

Tel: 91+9779550077,9779238252